

FIG.1A

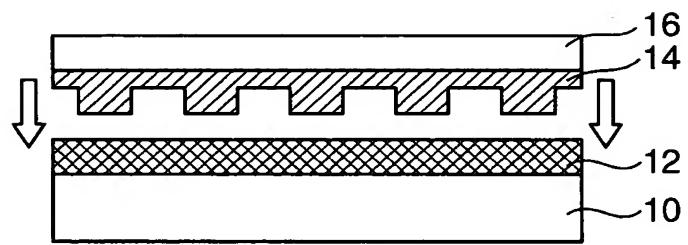


FIG.1B

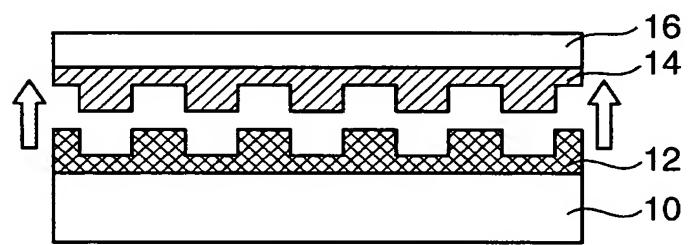


FIG.1C

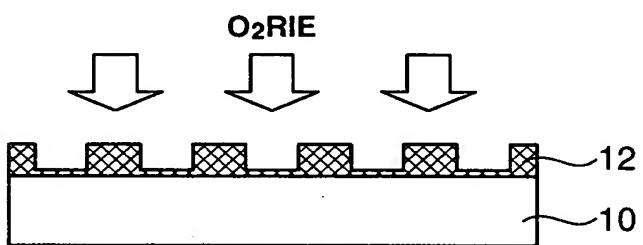


FIG.2A
INITIAL

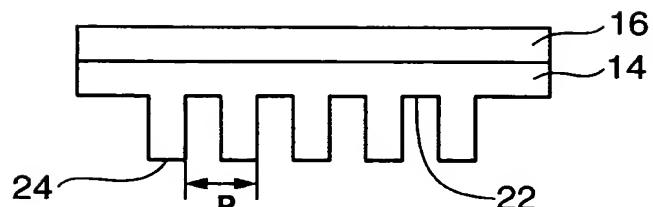


FIG.2B
TRANSFER

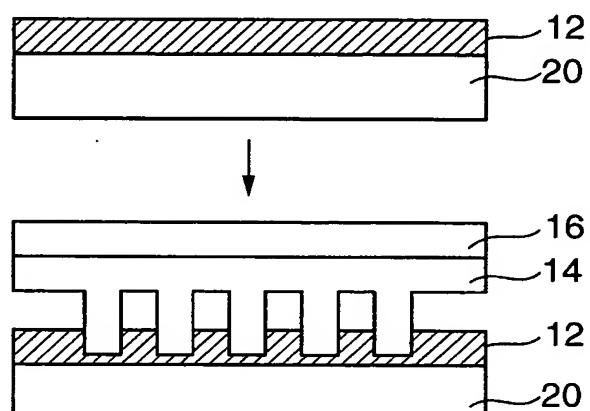


FIG.2C
SEPARATION

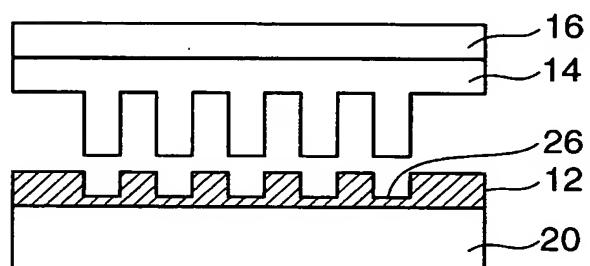


FIG.2D
RIE

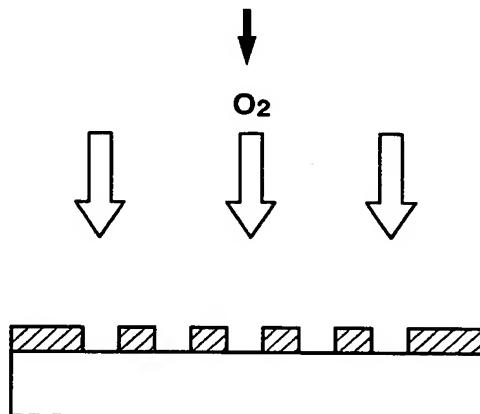


FIG.3A

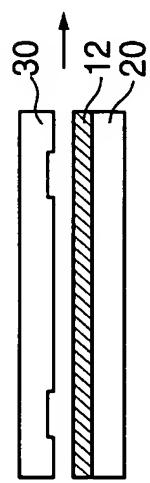


FIG.3B

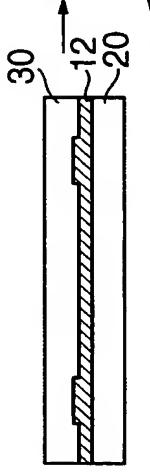


FIG.3C

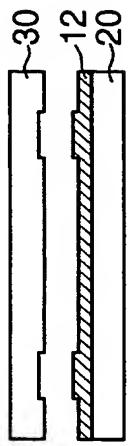


FIG.3D

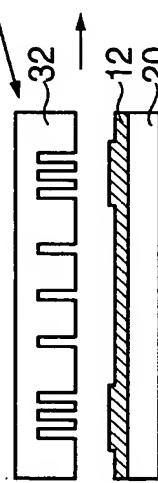


FIG.3E

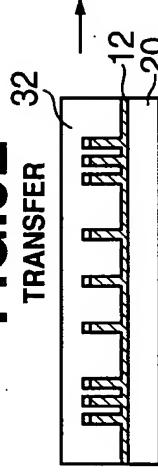


FIG.3F
SEPARATION

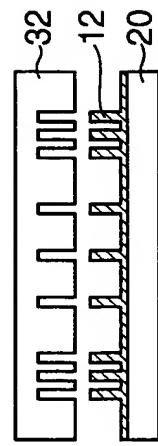


FIG.3G
 O_2 RIE

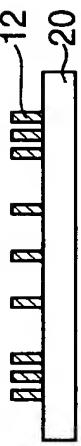


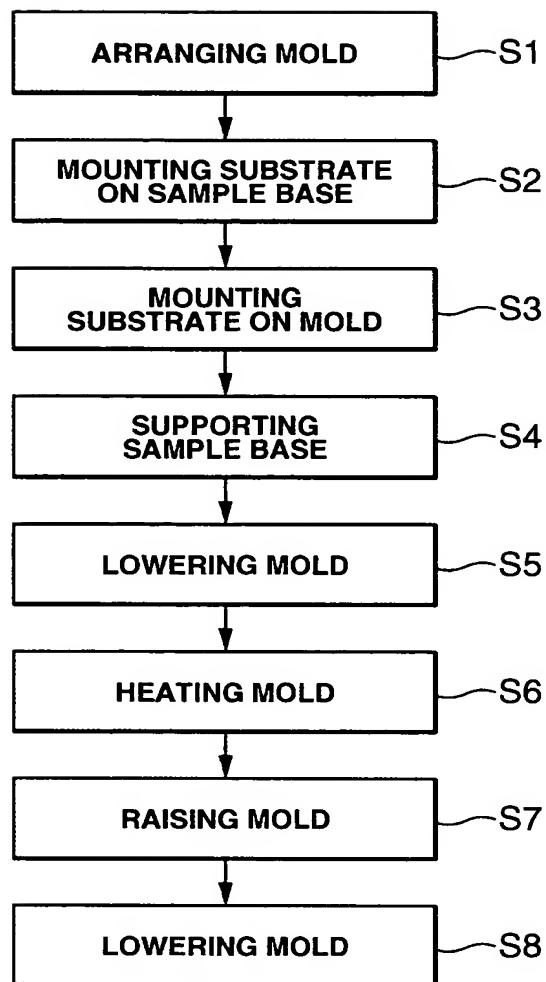
FIG.4

FIG.5A

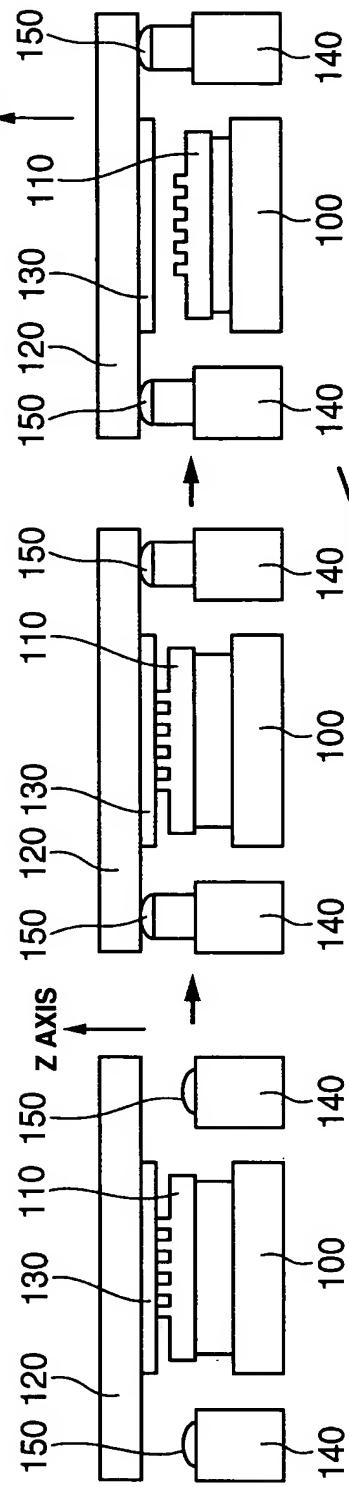


FIG.5B

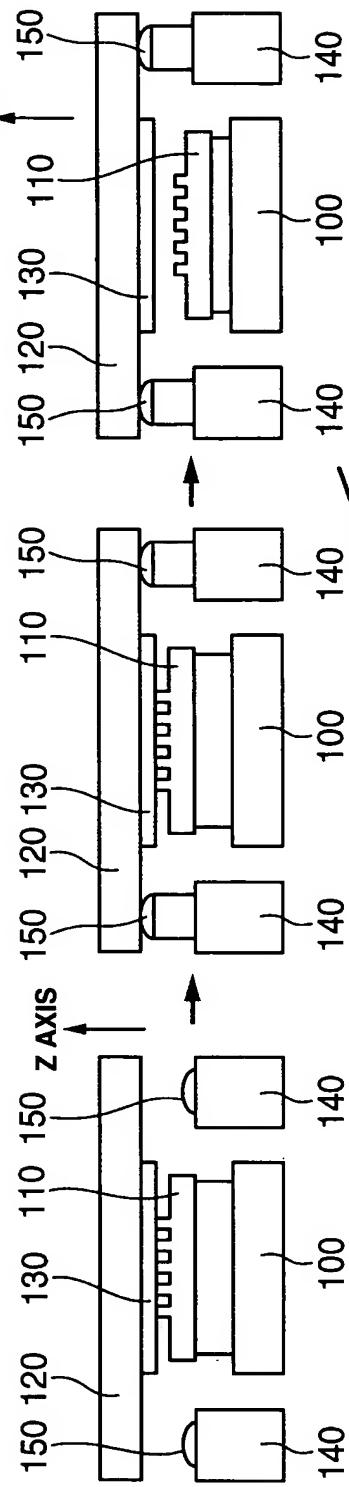


FIG.5C

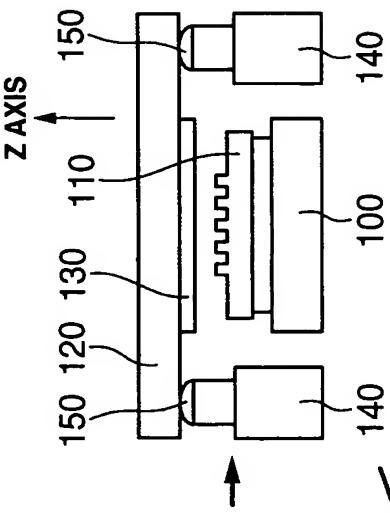


FIG.5D

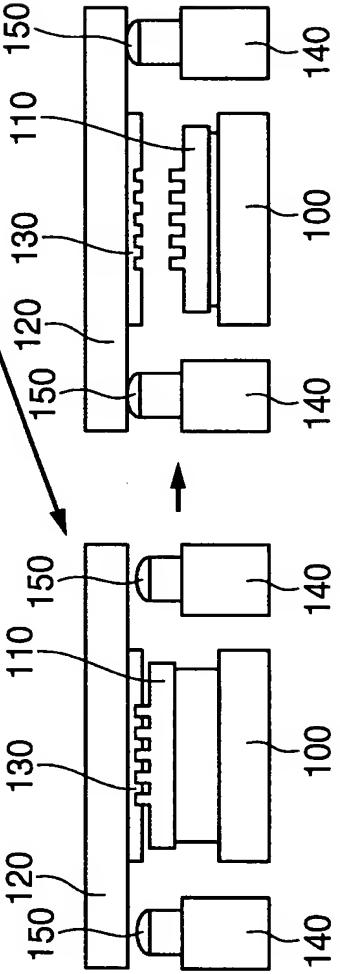


FIG.5E

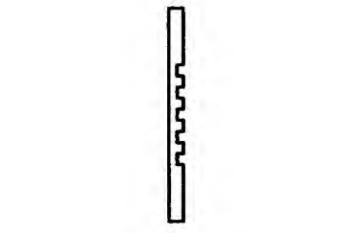


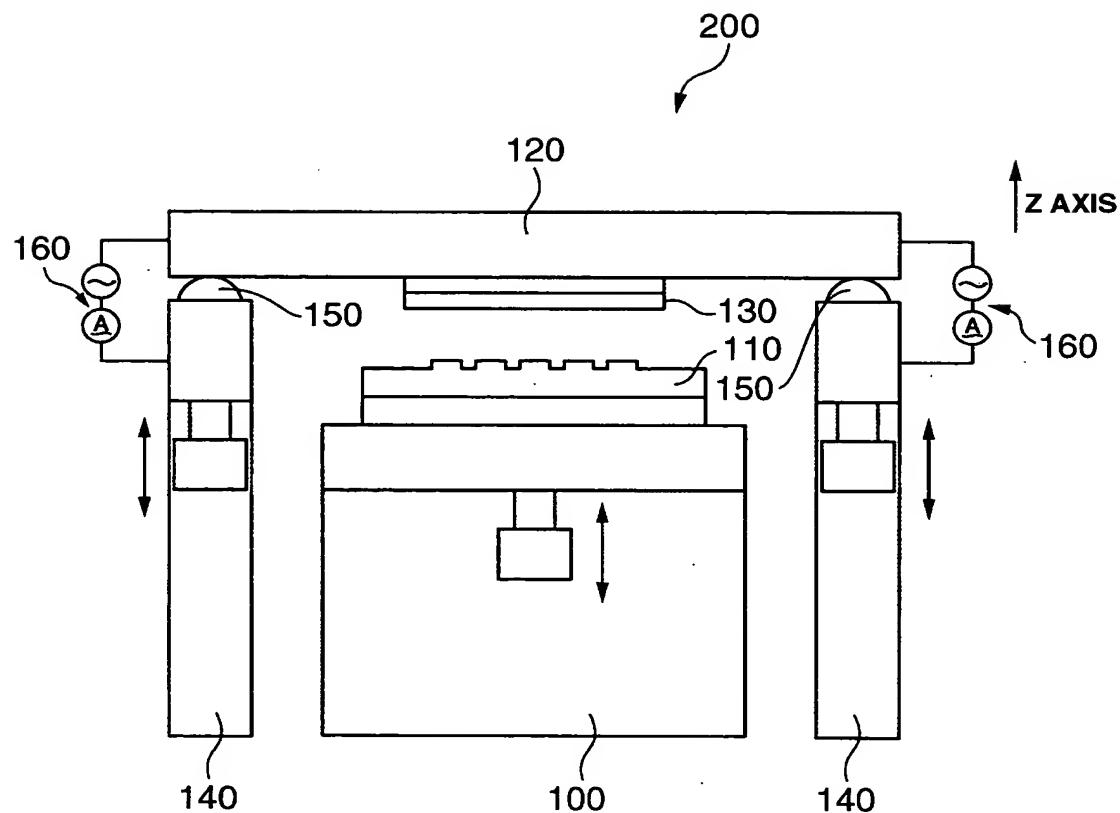
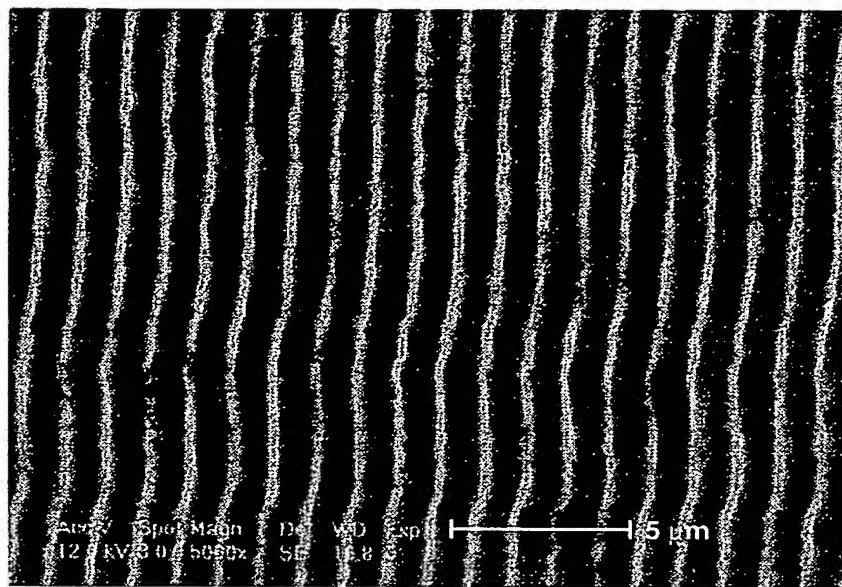
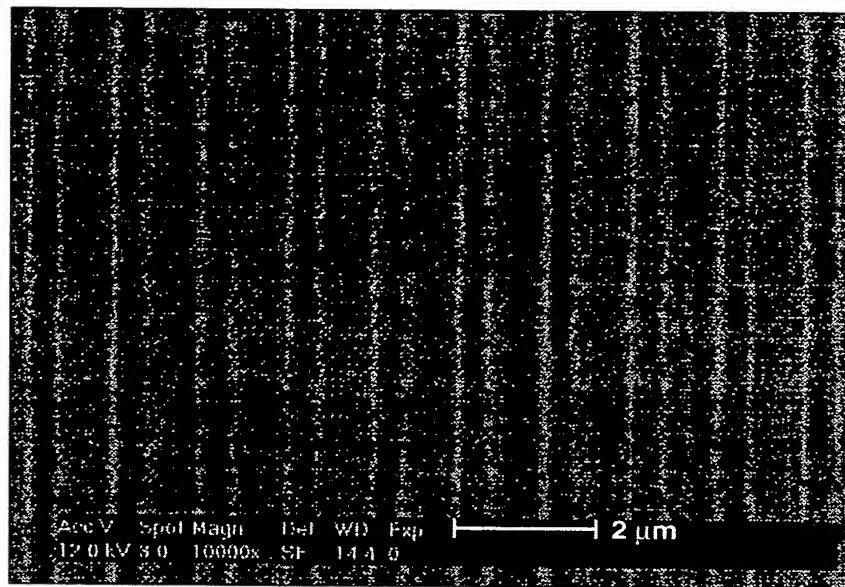
FIG.6

FIG.7



**MOLD TEMPERATURE: 130°C
FILM THICKNESS: 1 μm
SEM MAGNIFICATION FACTOR: 5000×**

FIG.8



**MOLD TEMPERATURE: 130°C
FILM THICKNESS: 200 nm
SEM MAGNIFICATION FACTOR: 10000×**